Specification for Approval
产品承认书

Customer:

Customer P/N:

VOOHU P/N: WHPL-1211A-231T0

Version No.: V0.1

Description: Power Line Choke

SUZHOU VOOHU Company Approval		Customer Approval (客户承认签章)
DRAWN	Geoffrey.Song	
CHECKED	Sunny.Xu	
APPROVED	Elvis. Song	
日期DATE:2026/4/30		日期DATE: 2026/4/30

Please Return One Copy to Us After Approved,TKs!（承认后请回寄一份,谢谢）

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Revision History

Revision	Changed Date	Request By	Change Content
V0.1	2026/04/30	Ryan	New Version Release

1 Features And Benefits

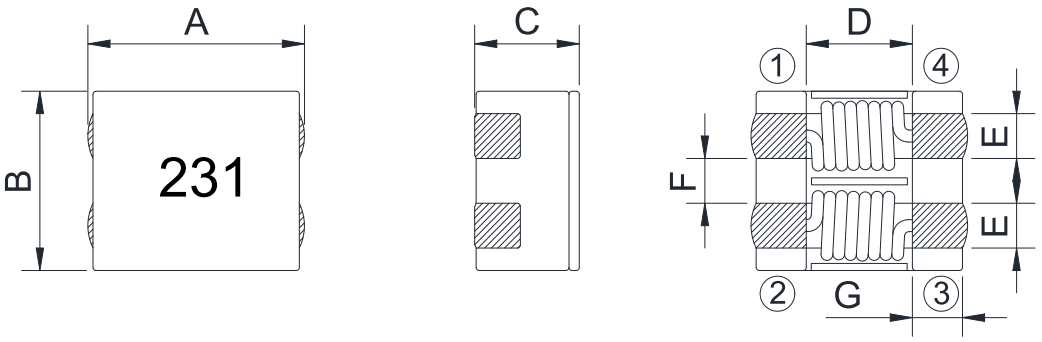


- Wire wound constructure common mode choke with best EMI suppression effect high impedance but very high rated current and low DCR
- Preventive measure against common mode noise radiation emissions from power line or else.
- Best for high current power devicedesign.
- Dimensions L x W x H = 12.0 x 10.8 x 6.6mm
- Operating Temperature: -40℃ to +105℃
- Compatible with RoHS Directive

2 Electrical Specifications @ 25°C

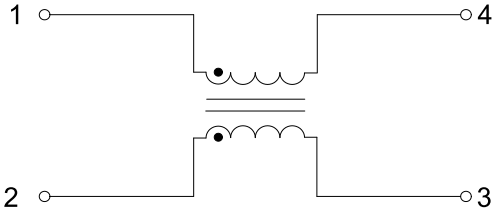
Part Number	Common Mode Impedance (100MHZ)		DCR (mΩ)Max	Rated Current (A)	Insulation Resistance (MΩ) Min	Rated Voltage (V) Max
	（Ω） Min	（Ω） Typ				
WHPL-1211A-231T0	80	230	4	10	10	125

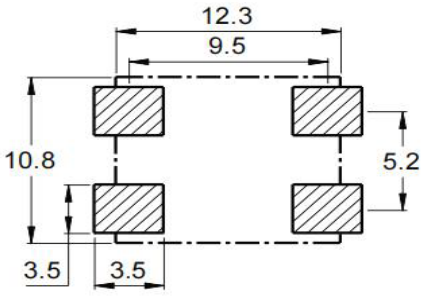
3 Dimensions (mm)& recommend layout



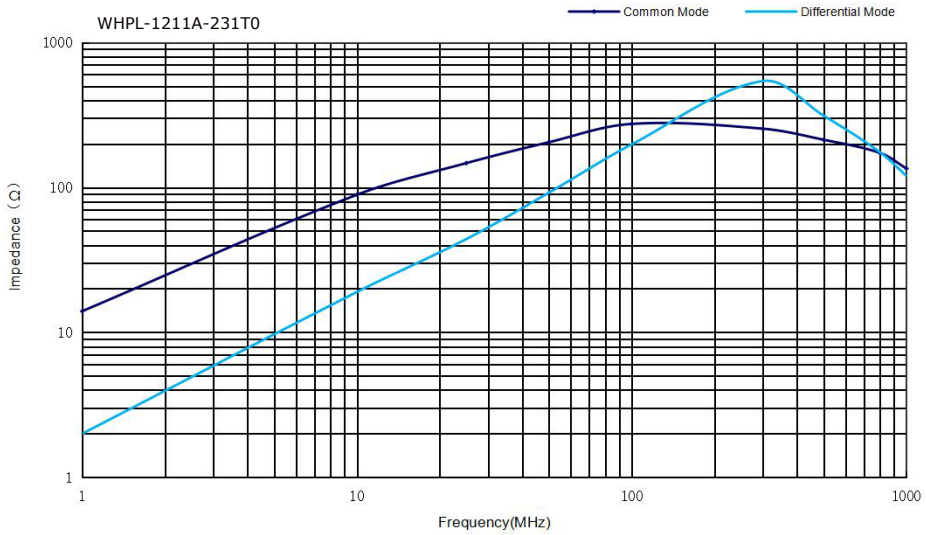
Item	A	B	C	D	E	F	G
Dim	12.1	10.8	6.5	7	2.7	2.5	2.5
Tole	±0.5	±0.5	Max	Typ	±0.4	±0.3	±0.3

4 Schematics

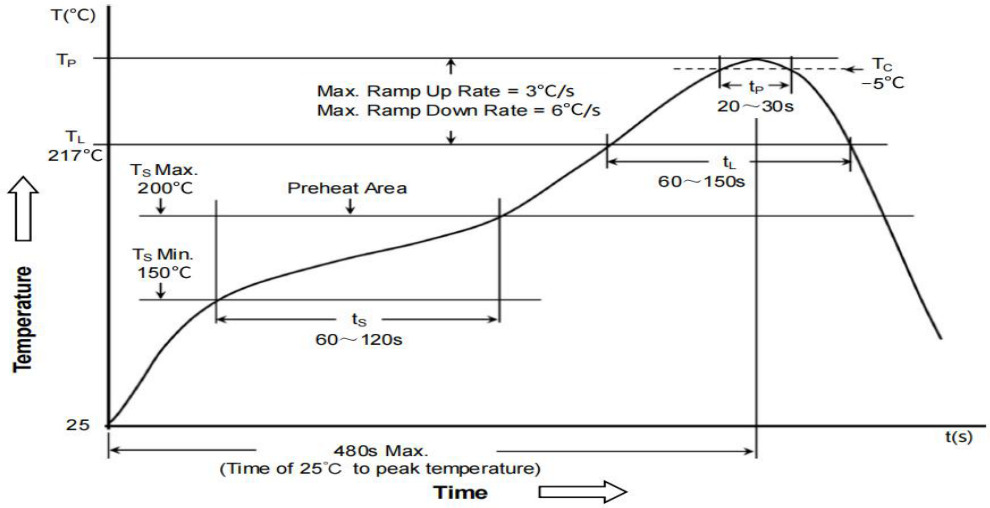




5 Impedance VS. Frequency

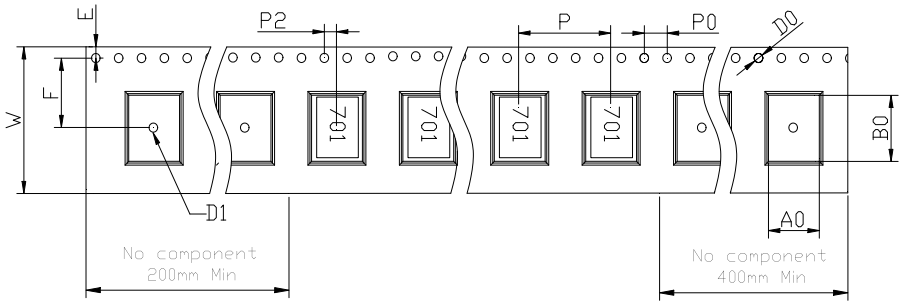


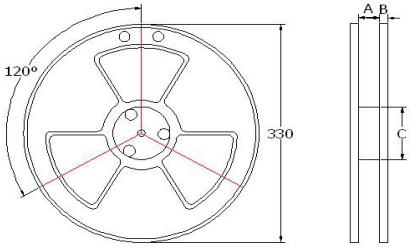
6 Recommended Reflow Profile



	Package Thickness	Package Volume		
		<350 mm3	350~2000 mm3	>2000 mm3
PB-Free Assembly	<1.6mm	260℃	260℃	260℃
	1.6~2.5mm	260℃	250℃	245℃
	≥2.5mm	250℃	245℃	245℃

7 Packaging specification





TYPE	A	B	C
1211	24.5	2.3	100

TYPE	W	A0	B0	K0	P	P0	P2	F	E	D0	D1	REEL (PCS)
WHPL-1211A	24.0	11.30	13.00	6.60	16.0	4.00	2.0	11.50	1.75	1.50	1.50	500

Package Quantity:
One Reel=500 Pcs
One Inner Carton=500*2=1000 Pcs
One Export Carton=1000*3=3000 Pcs

8 Reliability test

NO.	Test Item	Standard Reference	Test Condition
1	High temperature storage test	IPC/JEDEC J-STD-020D	Temperature：125±2℃ Time：168 hours Measurement at 24±4 hours after test conclusion.
2	Low temperature test	IPC/JEDEC J-STD-020D	Temperature：-40±2℃ Time：168 hours Measurement at 24±4 hours after test conclusion.
3	Constant temperature and constant humidity test	GB/T 2423.3 (IEC 60068-2-78)	Temperature: 40±2℃ / humidity:93±2%RH Time: 168 hours Measurement at 24±4 hours after test conclusion.
4	High temperature and high humidity test	GB/T 2423.50	Temperature: 85±2℃ / humidity:85±2%RH Time: 168 hours Measurement at 24±4 hours after test conclusion.
5	Thermal shock test	IPC/JEDEC J-STD-020D	First -40±5℃ for 30±2 minutes，last 125℃ 30±2 minutes as 1 cycle. Total 100 cycles.
6	Salt spray test	GB/T2423.17 (IEC 60068-2-11	Concentration :(5±0.1) % PH : 6.5 ~ 7.2 Temperature: 35 ±2 ℃ Time: 24 hours
7	Solder ability test	GB/T 2423.28 (IEC 60068-2-20)	Preheating: 150±5℃, 60 seconds Immerse the terminal in flux for 5 seconds.then dip the terminal into a soldering bath of 245±5℃ for 2±0.5 seconds.
8	Drop test	GB/T 2423.8 (IEC 60068-2-32)	Floor should be hard,strong,concrete. Height:0.8m. Test 6 surfaces , 3 ridges and 1 corner of Test-box.

9	Vibration test	GB/T 4857.7	Apply frequency 10~100~10Hz 1.52mm±10% amplitude in each of perpendicular direction for 20 minutes. Total 12 cycles
10	Soldering resistance test	GB/T 2423.50	Preheating: 150±5℃, 60~120 seconds dip the terminal into a soldering bath of 260±5℃ for 10±3 seconds with 3 times.
11	Terminal strength	MIL-STD-202	PCB specification: 100mm X 40mm. 4 layer board Thickness: 1.60 + / - 0.2 mm 1、>0805 inch/2012mm ：9.8N（1kg） 2、<=0805 inch/2012mm：4.9N（0.5kg） Hold time：60±1 s
12	Plate bending test	MIL-STD-202	PCB specification: 100mm X 40mm. 4 layer board Thickness: 1.60 + / - 0.2 mm Displacement: 2mm Hold time: 60±1s

REMINDERS

- The best assembly quality guarantee period of product: 12 months (From shipment date)
  Storage condition : seal in packaging, (temperature: 5 to 40°C, humidity: 10 to 75% RH or less).
- If taking out for use, the remaining products should be sealed in plastic bags and preserved in accordancewith the above conditions, to avoid oxidation of electrodes and affect soldering status.
- Do not use or store in locations where there are conditions such as gas corrosion (salt, acid, alkali, etc.).
- Before soldering, be sure to preheat components.
  The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Always handle products with care to avoid damage.
- Do not touch electrodes with bare hands directly, as oil secretions may inhibit soldering.
  Always ensure optimum conditions for soldering.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications.If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Use a wrist band to discharge static electricity in your body through the grounding wire.
- Do not expose the products to magnets or magnetic fields.
- Do not use for a purpose outside of the contents regulated in the delivery specifications.